

# 4.5V Drive Nch MOSFET

## RMW180N03

### ● Structure

Silicon N-channel MOSFET

### ● Features

- 1) High Power package(PSOP8).
- 2) High-speed switching, Low On-resistance.
- 3) Low voltage drive(4.5V drive).

### ● Application

Switching

### ● Packaging specifications

| Type      | Package                      | Taping |
|-----------|------------------------------|--------|
|           | Code                         | TB     |
|           | Basic ordering unit (pieces) | 2500   |
| RMW180N03 |                              | ○      |

### ● Absolute maximum ratings (Ta = 25°C)

| Parameter                      |            | Symbol      | Limits      | Unit |
|--------------------------------|------------|-------------|-------------|------|
| Drain-source voltage           |            | $V_{DS}$    | 30          | V    |
| Gate-source voltage            |            | $V_{GS}$    | $\pm 20$    | V    |
| Drain current                  | Continuous | $I_D$       | $\pm 18$    | A    |
|                                | Pulsed     | $I_{DP}$ *1 | $\pm 72$    | A    |
| Source current<br>(Body Diode) | Continuous | $I_S$       | 2.5         | A    |
|                                | Pulsed     | $I_{SP}$ *1 | 72          | A    |
| Power dissipation              |            | $P_D$ *2    | 3.0         | W    |
| Channel temperature            |            | Tch         | 150         | °C   |
| Range of storage temperature   |            | Tstg        | -55 to +150 | °C   |

 \*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$ 

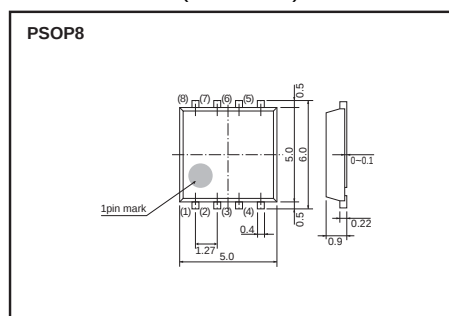
\*2 MOUNTED ON 40mm × 40mm Cu BOARD

### ● Thermal resistance

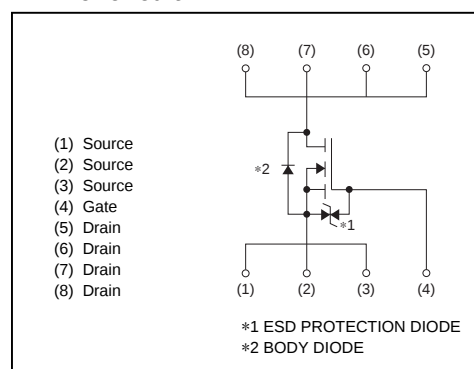
| Parameter          | Symbol      | Limits | Unit   |
|--------------------|-------------|--------|--------|
| Channel to Ambient | Rth (ch-a)* | 41.7   | °C / W |

\* MOUNTED ON 40mm × 40mm Cu BOARD

### ● Dimensions (Unit : mm)



### ● Inner circuit



## ● Electrical characteristics (Ta = 25°C)

| Parameter                               | Symbol         | Min. | Typ. | Max.     | Unit      | Conditions                      |
|-----------------------------------------|----------------|------|------|----------|-----------|---------------------------------|
| Gate-source leakage                     | $I_{GSS}$      | -    | -    | $\pm 10$ | $\mu A$   | $V_{GS} = \pm 20V, V_{DS} = 0V$ |
| Drain-source breakdown voltage          | $V_{(BR)DSS}$  | 30   | -    | -        | V         | $I_D = 1mA, V_{GS} = 0V$        |
| Zero gate voltage drain current         | $I_{DSS}$      | -    | -    | 1        | $\mu A$   | $V_{DS} = 30V, V_{GS} = 0V$     |
| Gate threshold voltage                  | $V_{GS(th)}$   | 1.0  | -    | 2.5      | V         | $V_{DS} = 10V, I_D = 1mA$       |
| Static drain-source on-state resistance | $R_{DS(on)}$ * | -    | 4.0  | 5.6      | $m\Omega$ | $I_D = 18A, V_{GS} = 10V$       |
|                                         |                | -    | 5.5  | 7.7      |           | $I_D = 18A, V_{GS} = 4.5V$      |
| Forward transfer admittance             | $ Y_{fs} $ *   | 15   | -    | -        | S         | $I_D = 18A, V_{DS} = 10V$       |
| Input capacitance                       | $C_{iss}$      | -    | 1250 | -        | pF        | $V_{DS} = 15V$                  |
| Output capacitance                      | $C_{oss}$      | -    | 400  | -        | pF        | $V_{GS} = 0V$                   |
| Reverse transfer capacitance            | $C_{rss}$      | -    | 145  | -        | pF        | $f = 1MHz$                      |
| Turn-on delay time                      | $t_{d(on)}$ *  | -    | 14   | -        | ns        | $I_D = 9A, V_{DD} \approx 15V$  |
| Rise time                               | $t_r$ *        | -    | 39   | -        | ns        | $V_{GS} = 10V$                  |
| Turn-off delay time                     | $t_{d(off)}$ * | -    | 39   | -        | ns        | $R_L = 1.67\Omega$              |
| Fall time                               | $t_f$ *        | -    | 12   | -        | ns        | $R_G = 10\Omega$                |
| Total gate charge                       | $Q_g$ *        | -    | 24   | -        | nC        | $I_D = 18A, V_{DD} \approx 15V$ |
| Gate-source charge                      | $Q_{gs}$ *     | -    | 4.4  | -        | nC        | $V_{GS} = 10V$                  |
| Gate-drain charge                       | $Q_{gd}$ *     | -    | 4.7  | -        | nC        |                                 |

\*Pulsed

## ● Body diode characteristics (Source-Drain) (Ta = 25°C)

| Parameter       | Symbol     | Min. | Typ. | Max. | Unit | Conditions                |
|-----------------|------------|------|------|------|------|---------------------------|
| Forward Voltage | $V_{SD}$ * | -    | -    | 1.2  | V    | $I_S = 2.5A, V_{GS} = 0V$ |

\*Pulsed

●Electrical characteristic curves (Ta=25°C)

Fig.1 Typical Output Characteristics( I )

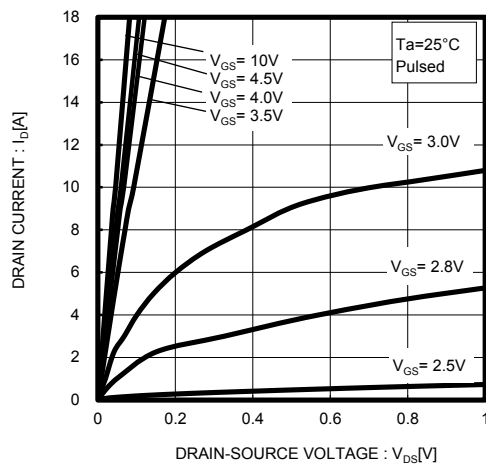


Fig.2 Typical Output Characteristics( II )

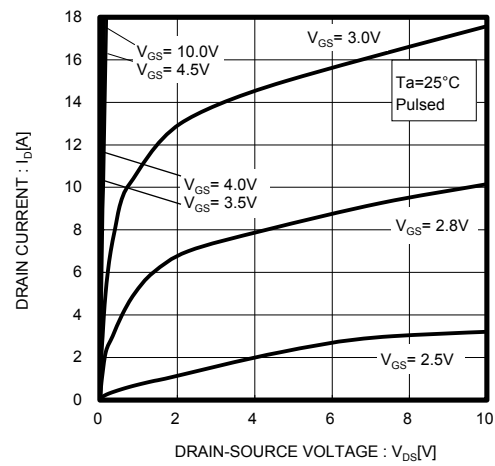


Fig.3 Typical Transfer Characteristics

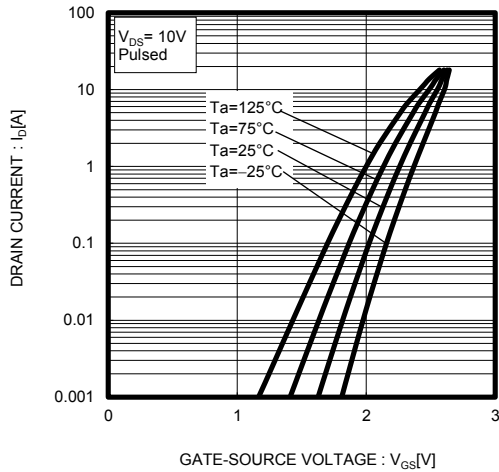


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

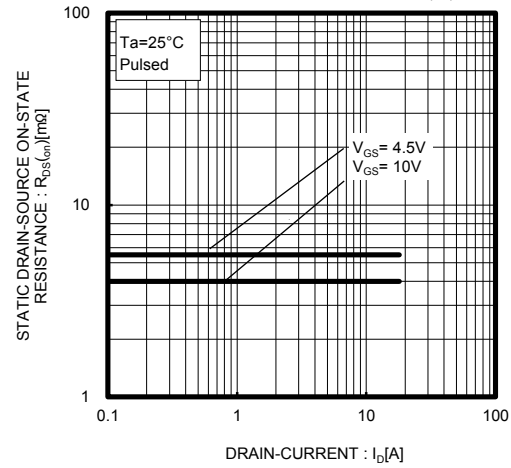


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

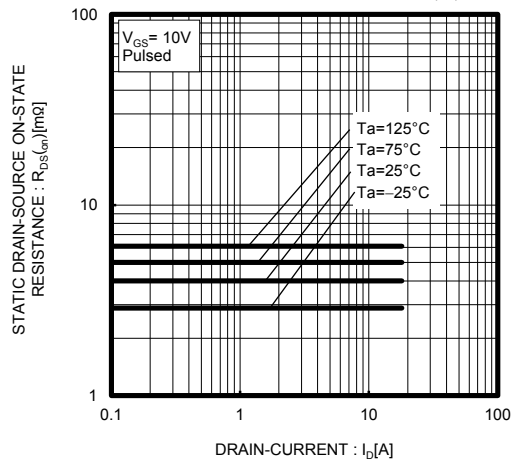


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( III )

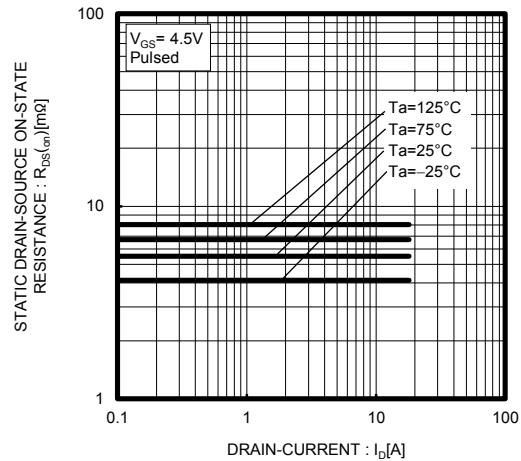


Fig.7 Forward Transfer Admittance vs. Drain Current

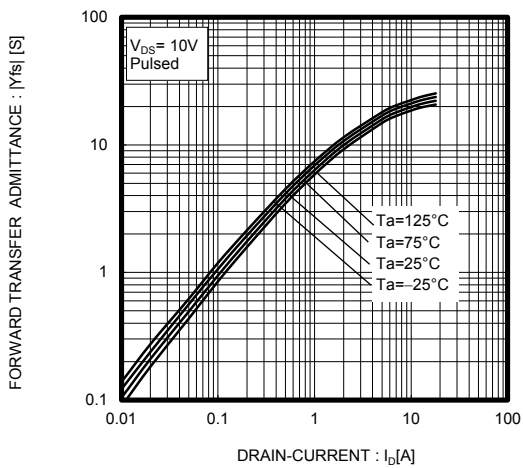


Fig.8 Reverse Drain Current vs. Source-Drain Voltage

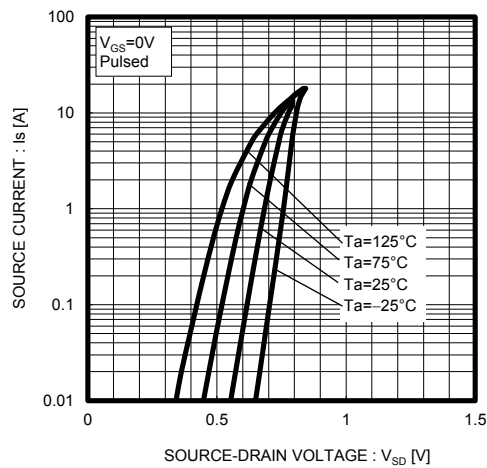


Fig.9 Static Drain-Source On-State Resistance vs. Gate Source Voltage

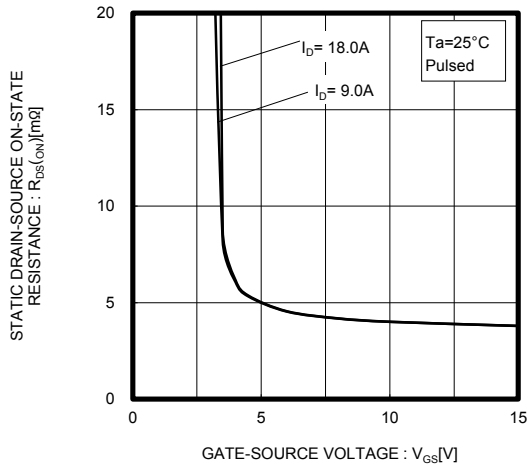


Fig.10 Switching Characteristics

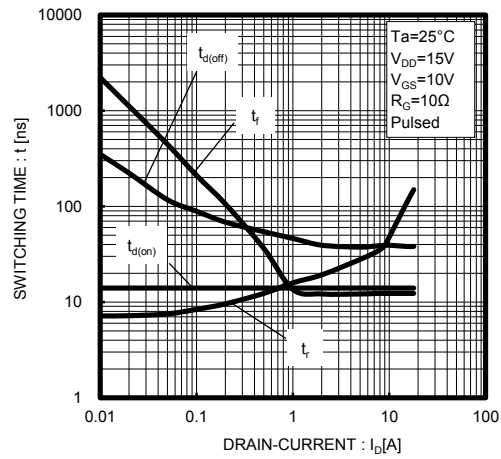


Fig.11 Dynamic Input Characteristics

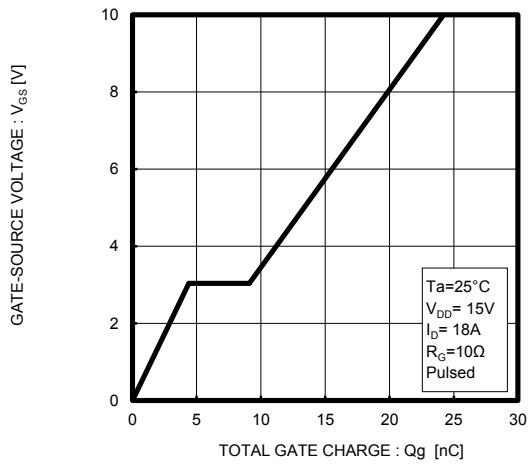


Fig.12 Typical Capacitance vs. Drain-Source Voltage

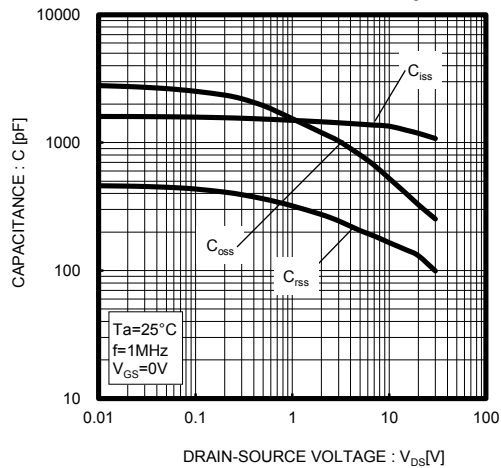


Fig.13 Maximum Safe Operating Area

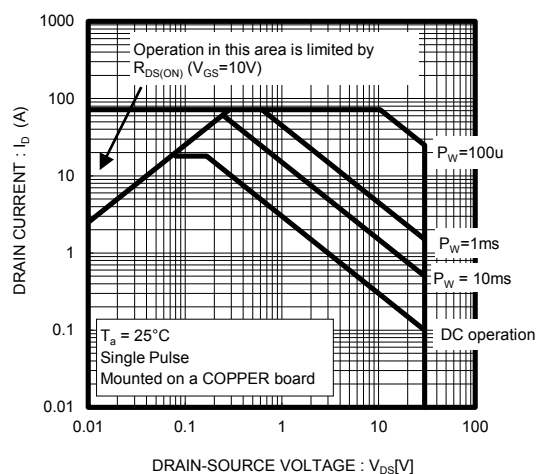
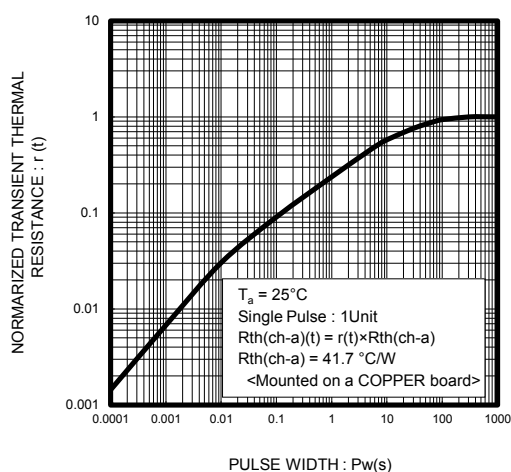


Fig.14 Normalized Transient Thermal Resistance vs. Pulse Width



## ● Measurement circuits

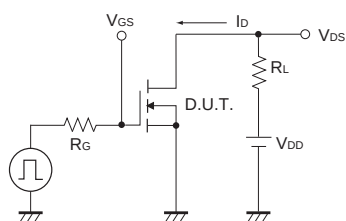


Fig.1-1 Switching Time Measurement Circuit

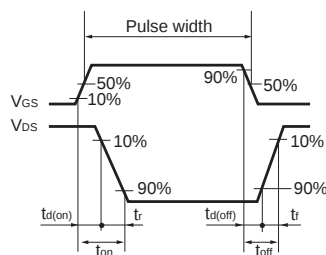


Fig.1-2 Switching Waveforms

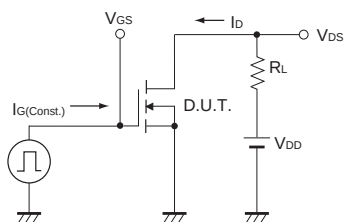


Fig.2-1 Gate Charge Measurement Circuit

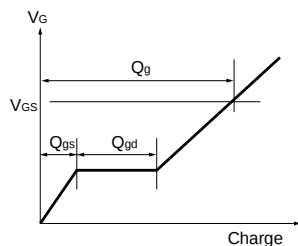


Fig.2-2 Gate Charge Waveform

## ● Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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